



# SOT129-1

plastic dual in-line package; 40 leads (600 mil)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DIP40
<b>Package type industry code</b>	DIP40
<b>Package style descriptive code</b>	DIP (dual in-line package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	051G08
<b>JEDEC package outline code</b>	MO-015
<b>JEITA package outline code</b>	SC-511-40
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	13-2-2003

Table 1. Package summary

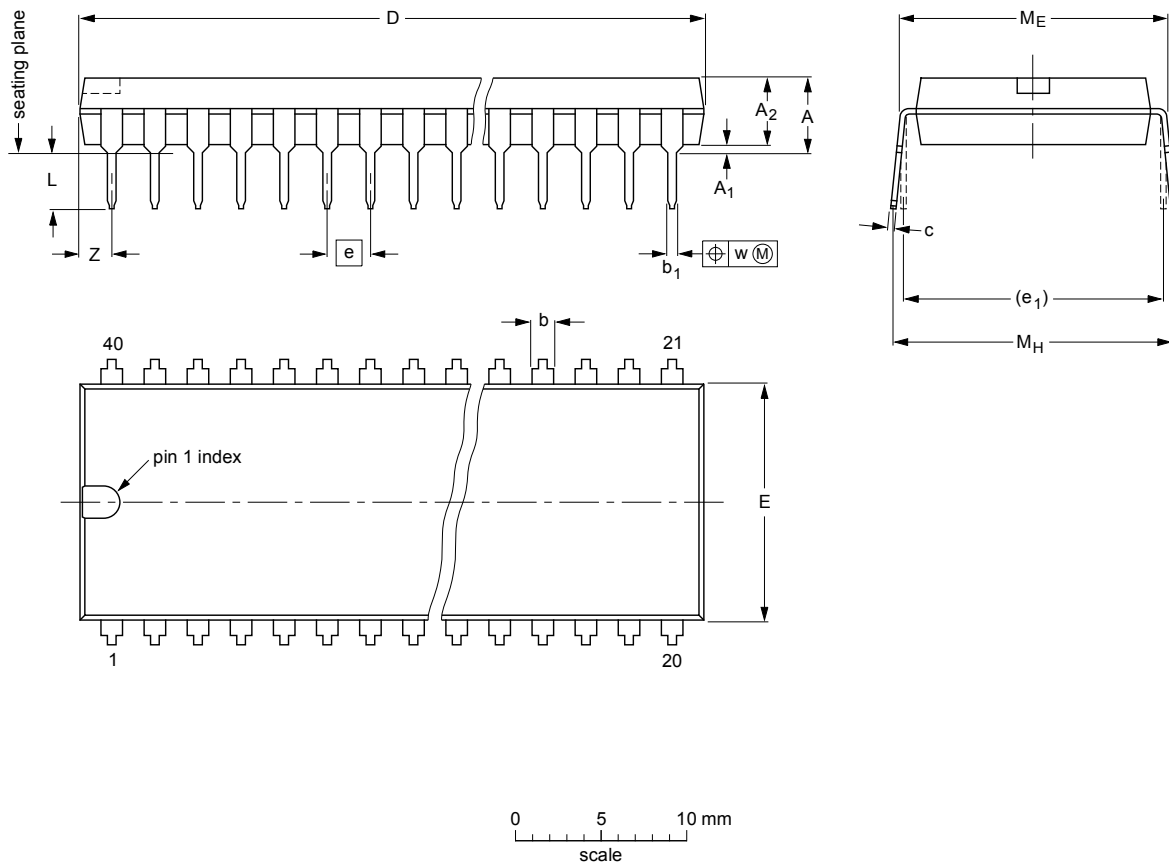
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	51.5	-	52	52.5	mm
E	package width	13.7	-	13.8	14.1	mm
A	seated height	[tbd]	-	4.7	4.7	mm
A <sub>2</sub>	package height	[tbd]	-	3.85	4	mm
n <sub>2</sub>	actual quantity of termination	-	-	40	-	



## 2. Package outline

DIP40: plastic dual in-line package; 40 leads (600 mil)

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.7	0.51	4	1.70 1.14	0.53 0.38	0.36 0.23	52.5 51.5	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.02	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.1	0.6	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

**Note**

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT129-1	051G08	MO-015	SC-511-40		99-12-27 03-02-13

Fig. 1. Package outline DIP40 (SOT129-1)

### 3. Legal information

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